

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Title:: Raised Solder-Mask-Defined (SMD)
Solder Ball Pads For A Laminate
Electronic Circuit Board
Attorney Docket Number:: TI-36052 (1962-07500)
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure:: 1
Total Drawing Sheets:: 7
Small Entity?:: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: Taiwan
Status:: Full Capacity
Given Name:: Tz-Cheng
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Applicant Authority type:: Inventor

Primary Citizenship Country:: India
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Correspondence Information

Correspondence Customer Number:: 23494

Representative Information

Representative Customer Number:: 23494

Assignee Information

Assignee name:: Texas Instruments Incorporated
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